

**Amendments To The Specification**

***Please replace paragraph [0001] with the following amended paragraph:***

[0001] This application is a continuation of application Serial No. 10/214,740, filed August 9, 2002, entitled Liquid Manufacturing Processes for Panel Layer Fabrication, which is a continuation-in-part of ~~co-pending~~ application Serial No. 09/697,344, filed October 27, 2000, now U.S. Patent No. 6,612,889, entitled ~~A Method for Making a Light-Emitting Panel and Method for Making~~, and is related to the following co-owned, ~~co-pending~~ applications: Ser. No. 09/697,346, now U.S. Patent No. 6,545,422, filed October 27, 2000, entitled: ~~A Socket for Use with a Micro-Component in a Light-Emitting Panel~~; Ser. No. 09/697,358, filed October 27, 2000, entitled: ~~A Micro-Component for Use in a Light-Emitting Panel~~; Ser. No. 09/697,498, filed October 27, 2000, now U.S. Patent No. 6,620,012, entitled: ~~A Method for Testing a Light-Emitting Panel and the Components Therein~~; Ser. No. 09/697,345, filed October 27, 2000, now U.S. Patent No. 6,570,335, entitled: ~~A Method and System for Energizing a Micro-Component In a Light-Emitting Panel~~; Ser. No. 10/\_\_\_\_\_, 214,769, filed August 9, 2002, entitled Use of Printing and Other Technology for Micro-Component Placement ~~filed herewith~~ (Attorney Dock. No. SAIC0029-CIP2 or 36609/268977); Ser. No. 10/\_\_\_\_\_, 214,716, filed August 9, 2002, entitled Method of On-Line Testing of a Light-Emitting Panel ~~filed herewith~~ (Attorney Dock. No. SAIC0025-CIP); Ser. No. 10/\_\_\_\_\_, 214,764, filed August 9, 2002, entitled Method and Apparatus for Addressing Micro-Components in a Plasma Display Panel ~~filed herewith~~ (Attorney Dock. No. SAIC0026-CIP); and Ser. No. 10/\_\_\_\_\_, 214,768, filed August 9, 2002, entitled Design, Fabrication, Conditioning, and Testing of Micro-Components for Use in a Light-Emitting Panel ~~filed herewith~~ (Attorney Dock. No. SAIC0027-CIP). Each of the above-identified applications is incorporated herein by reference in its entirety.

***Please replace paragraph [0033] with the following amended paragraph:***

[0033] In one embodiment, the micro-components 40 are positioned in the sockets 30 of first substrate 10 by use of an ink-jet-type feeder which provides aligned placement of the micro-components 40. A number of methods of placing the micro-components in the sockets are disclosed in co-pending application Serial No. 10/\_\_\_\_\_, 214,769

(Attorney Docket No. 36609/268977), which is incorporated herein by reference in its entirety.

***Please replace paragraph [0034] with the following amended paragraph:***

**[0034]** An adhesive or bonding agent, discussed below, may be applied to each micro-component to assist in placing/holding a micro-component 40 or plurality of micro-components in a socket 30. In an alternative embodiment, an electrostatic charge is placed on each micro-component and an electrostatic field is applied to each micro-component to assist in the placement of a micro-component 40 or plurality of micro-components in a socket 30. This technique, known as “electrostatic sheet transfer” (“EST”) is described in the aforementioned co-pending application Serial No. 10/\_\_\_\_214,769 (Attorney Docket No. 36609/268977.) Applying an electrostatic charge to the micro-components also helps avoid agglomeration among the plurality of micro-components. In one embodiment of the present invention, an electron gun may be used to place an electrostatic charge on each micro-component, then one electrode disposed proximate to each socket 30 is energized to provide the opposing electrostatic field required to attract the electrostatically charged micro-component.

***Please replace paragraph [0051] with the following amended paragraph:***

**[0051]** Methods for distributing the micro-components into the sockets include dispensing the micro-components using a placement tool, an ink jet-type printer, or a gravity-fed drop tower which is aligned with the sockets in the substrate. Alternatively, the substrate may be passed through one or more vibratory, e.g., ultrasonic, shaker baths containing an excess plurality of micro-components, i.e., a much larger number of micro-components than are needed to fill the available positions on the substrate. Such shakers are well known in the art and may include orbital shakers and other vibratory movements. The shaking causes the micro-components to be dispersed across the surface of the substrate so that a micro-component is disposed within each of the sockets. A further discussion of different methods for placement of the plurality of micro-components is provided in the aforementioned co-pending application Serial No. 10/\_\_\_\_214,769 (Attorney Docket No. ~~36608/2689~~36609/268977).

*Please replace paragraph [0059] with the following amended paragraph:*

[0059] Micro-components, which were separately formed in step 208 are placed in the sockets using an appropriate method as described in the afore-mentioned co-pending application Serial No. 10/\_\_\_\_214,769 (Attorney Docket No. SAIC0029-CIP2\_or 36609/268977). As previously described, the micro-components are typically coated with a phosphor material for visible light emission. In an exemplary embodiment of micro-component forming process step 208, the micro-components are coated with phosphor by immersing the micro-components in a bath containing a slurry of phosphor particles so that the particles adhere to the micro-component surface. The micro-components are then removed from the slurry and subjected to a curing process, e.g., a furnace, oven or other heat source, to remove any solvents that were used to form the slurry, leaving a solid phosphor coating on the micro-component surface.